



Symbols and parameters			Values	Units
$I_{T(AV)}$	Average on-state current	sin 180; $T_C = 85 (100)^\circ\text{C}$	819 (564)	A
I_{TRMS}	RMS on-state current	continuous operation	1500	A
V_{RSM}	Non-repetitive peak reverse voltage		2300	V
V_{RRM}	Repetitive peak reverse voltage		2200	V
V_{DRM}	Repetitive peak off-state voltage		2200	V
I_{TSM}	Surge on-state current	$T_j = 25^\circ\text{C}; 10 \text{ ms}$	30000	A
		$T_j = 125^\circ\text{C}; 10 \text{ ms}$	26500	A
I^2t	I^2t value, rating for fusing	$T_j = 25^\circ\text{C}; 10 \text{ ms}$	4500000	A^2s
		$T_j = 125^\circ\text{C}; 10 \text{ ms}$	3500000	A^2s
V_T	On-state voltage	$T_j = 125^\circ\text{C}; I_T = 3000 \text{ A}$	max. 1.51	V
$V_{T(TO)}$	On-state threshold voltage	$T_j = 125^\circ\text{C}$	max. 0.82	V
r_T	On-state slope resistance	$T_j = 125^\circ\text{C}$	max. 0.17	$\text{m}\Omega$
$I_{DD}; I_{RD}$	Forward off-state current; Direct reverse current	$T_j = 125^\circ\text{C}, V_{DD} = V_{DRM}; V_{RD} = V_{RRM}$	max. 150	mA
t_{gd}	Gate controlled turn-on delay time	$T_j = 25^\circ\text{C}; I_G = 1 \text{ A}; di_G/dt = 1 \text{ A}/\mu\text{s}$	max. 4	μs
$(di/dt)_{cr}$	Critical rate of rise of on-state current		200	$\text{A}/\mu\text{s}$
$(dv/dt)_{cr}$	Critical rate of rise of off-state voltage		1000	$\text{V}/\mu\text{s}$
t_q	Turn-off time		typ. 350	μs
I_H	Holding current	$T_j = 25^\circ\text{C}$	max. 500	mA
I_L	Latching current	$T_j = 25^\circ\text{C}; R_G = 33 \Omega$	max. 2500	mA
V_{GT}	Gate trigger voltage	$T_j = 25^\circ\text{C}; \text{d.c.}$	min. 2.2	V
I_{GT}	Gate trigger current	$T_j = 25^\circ\text{C}; \text{d.c.}$	min. 250	mA
V_{GD}	Gate non-trigger voltage	$T_j = 125^\circ\text{C}; \text{d.c.}$	max. 0.25	V
I_{GD}	Gate non-trigger current	$T_j = 125^\circ\text{C}; \text{d.c.}$	max. 10	mA
$R_{th(j-c)}$	Thermal resistance, junction to case	cont.; per chip / per module	0.0405	K/W
		sin.180; per chip / per module	0.042	K/W
		rec.120; per chip / per module	0.043	K/W
$R_{th(c-s)}$	Thermal resistance, junction to heatsink	per chip / per module	0.015	K/W
T_j	Junction temperature		-40 ... +125	$^\circ\text{C}$
T_{stg}	Storage temperature range		-40 ... +130	$^\circ\text{C}$
V_{isol}	Insulation test voltage (r.m.s.)	a.c. 50 Hz; r.m.s.; 1s / 1min.	3600 / 3000	$\text{V}\sim$
M_S	Mounting torque on heatsink	min. / max	5.1 / 6.9	Nm
M_t	Mounting torque for terminals	min. / max	16.2 / 19.8	Nm
a	Maximum allowable acceleration		5*9.81	m/s^2
W	Weight	approx.	1950	g

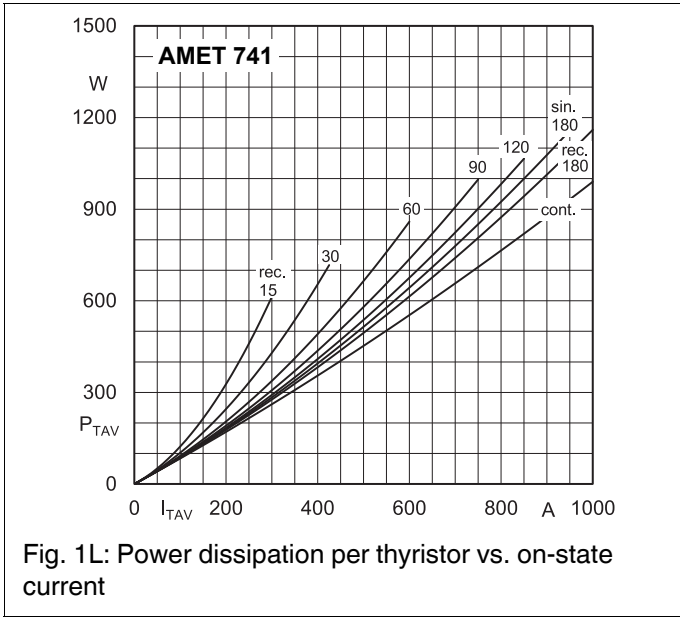


Fig. 1L: Power dissipation per thyristor vs. on-state current

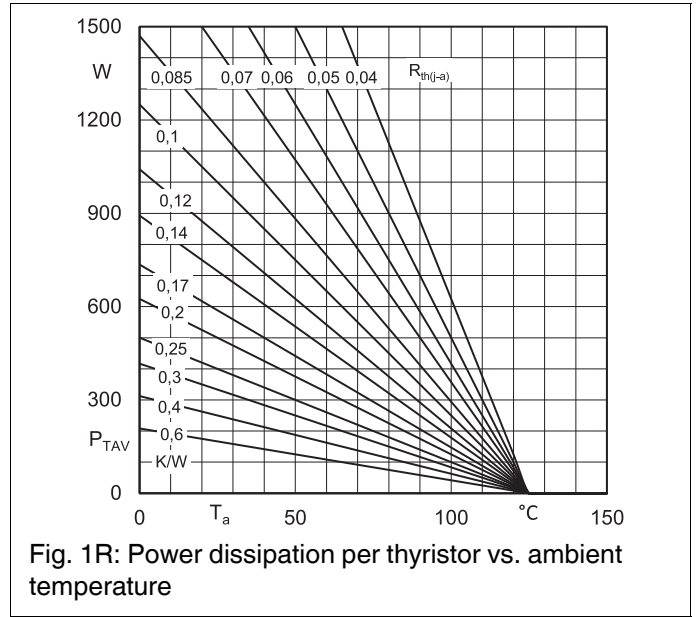


Fig. 1R: Power dissipation per thyristor vs. ambient temperature

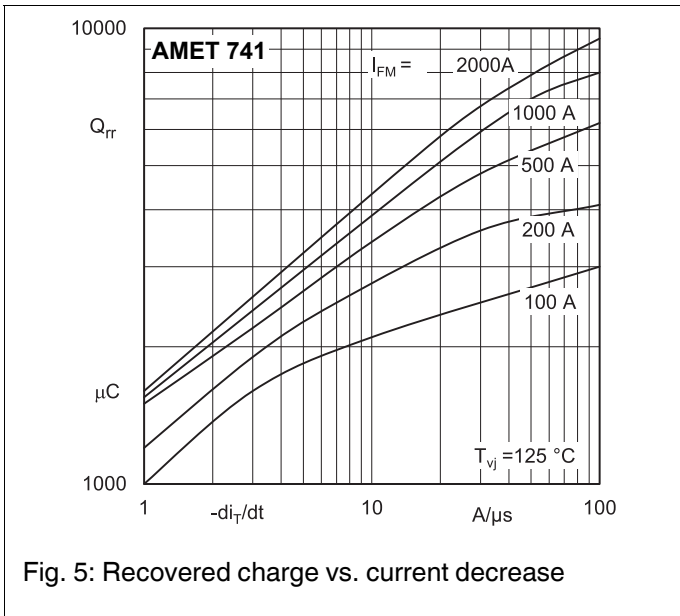


Fig. 5: Recovered charge vs. current decrease

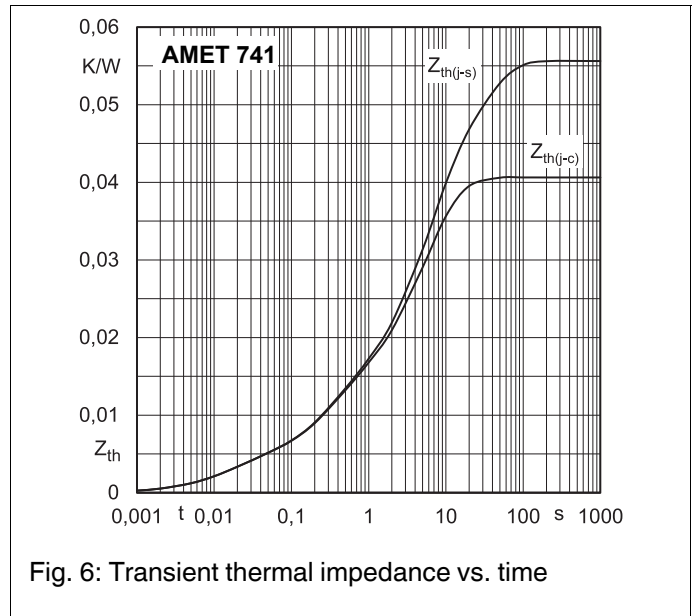


Fig. 6: Transient thermal impedance vs. time

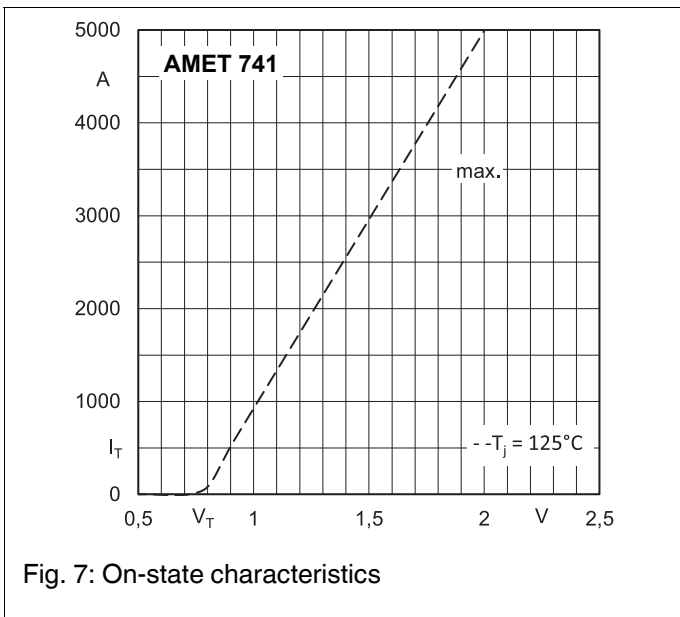


Fig. 7: On-state characteristics

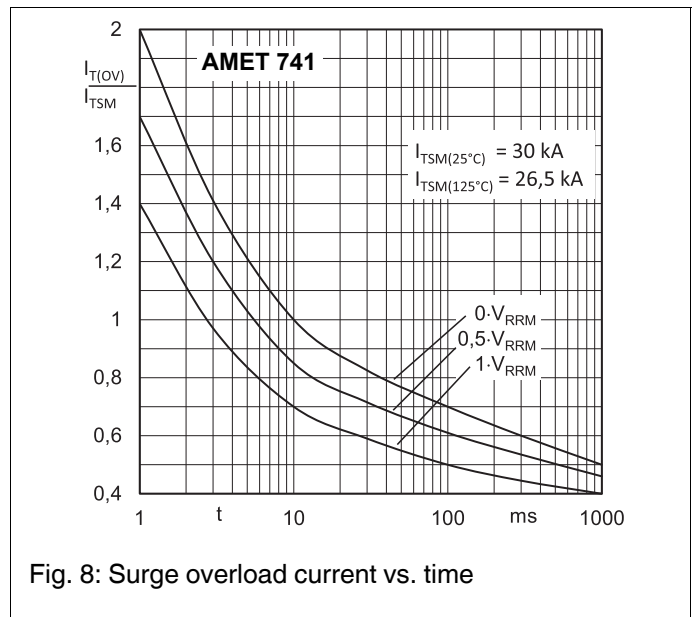


Fig. 8: Surge overload current vs. time

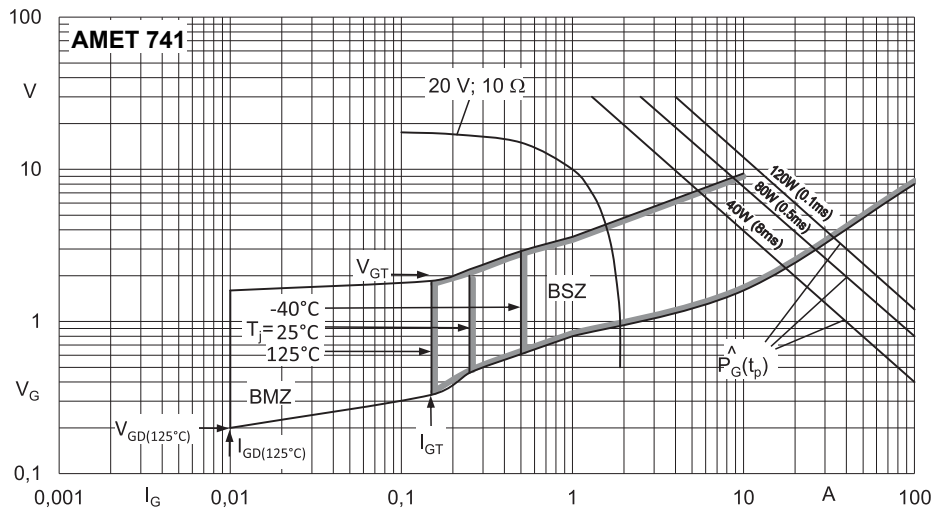
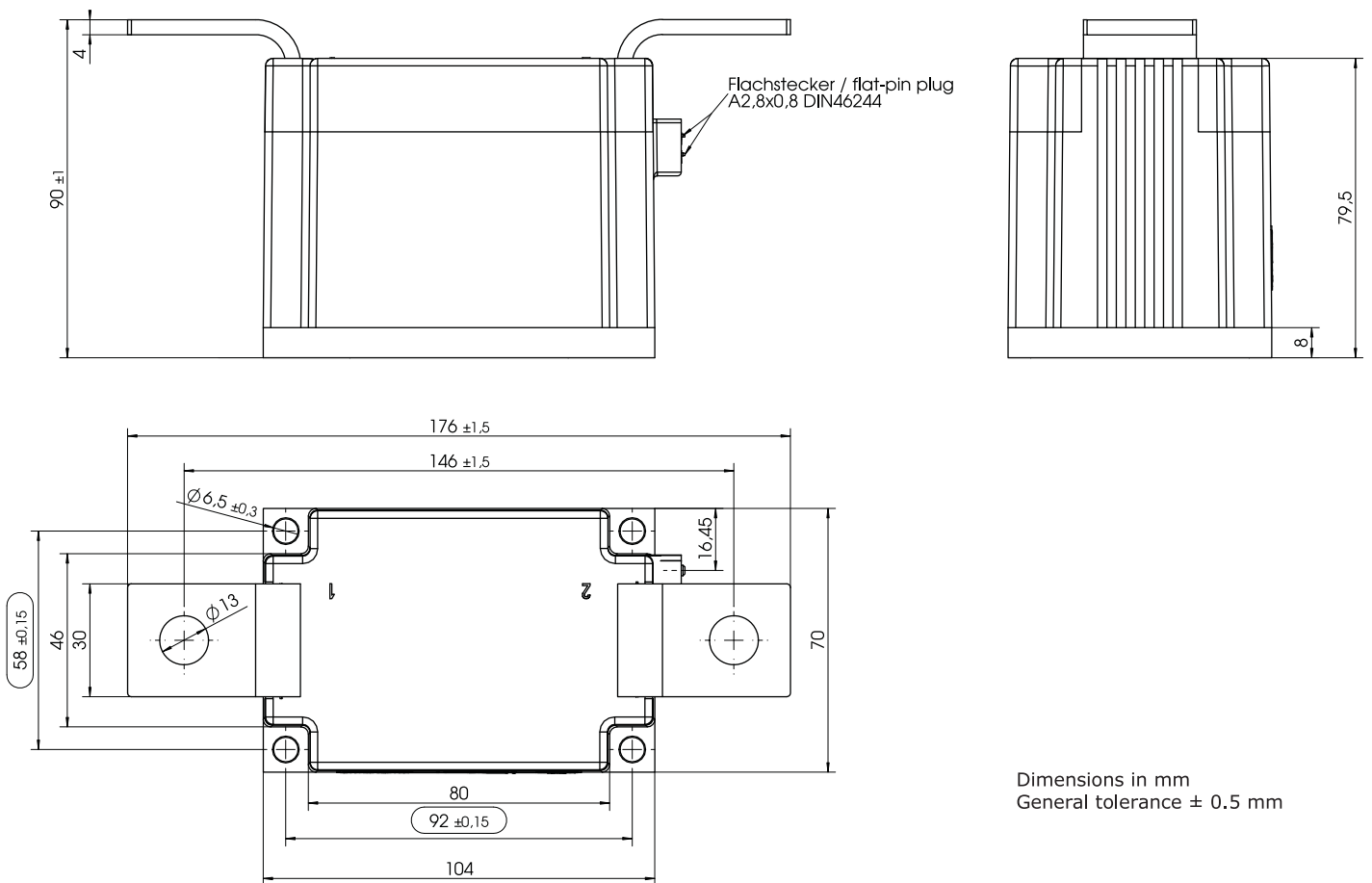


Fig. 9: Gate trigger characteristics

DIMENSIONS



TOPOLOGY OF INTERNAL CONNECTION

